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Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 53331

Application ID: 10667759



Title of Invention:

METHODS OF MAKING THIN
INTEGRATED CIRCUIT DEVICE
PACKAGES WITH IMPROVED
THERMAL PERFORMANCE

First Named Inventor: Sean Crowley

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-09-22

Effective Receipt Date: 2004-01-08

Submission Type: Information Disclosure
Statement

Filing Type:

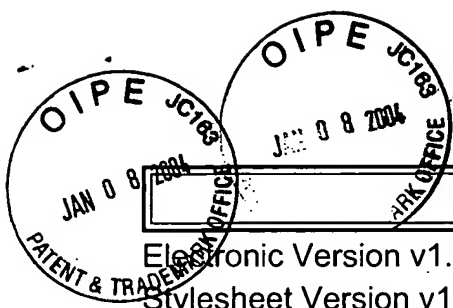
Confirmation number: 1384

Attorney Docket Number: AMKOR022CB

Total Fees Authorized:


Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark
Office,ou=Department of Commerce,o=U.S. Government,c=US

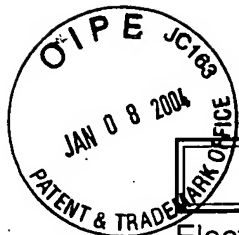
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Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	METHODS OF MAKING THIN INTEGRATED CIRCUIT DEVICE PACKAGES WITH IMPROVED THERMAL PERFORMANCE									
Application Number: 10/667759 										
Date: 2003-09-22										
First Named Applicant: Sean T. Crowley										
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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PERFORMANCE

Application Number: 10/667759



Confirmation Number: 1384

First Named Applicant: Sean Crowley

Attorney Docket Number: AMKOR022CB

Art Unit: 2811

Search string: (6395578 or 6400004 or 6410979 or 6414385
or 6420779 or 6429508 or 6437429 or 6444499
or 6448633 or 6452279 or 6464121 or 6476469
or 6476474 or 6482680 or 6498099 or 6498392
or 6507096 or 6507120 or 6534849 or 6559525
or 6566168).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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	2	6400004	2002-06-04	FAN ET AL.			
	3	6410979	2002-06-25	ABE			
	4	6414385	2002-07-02	HUANG ET AL.			
	5	6420779	2002-07-16	SHARMA ET AL.			
	6	6429508	2002-08-06	GANG			
	7	6437429	2002-08-20	SU ET AL.			
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	9	6448633	2002-09-10	YEE ET AL.			
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Signature

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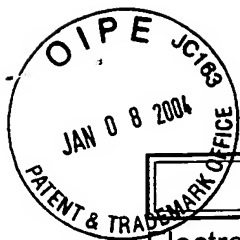
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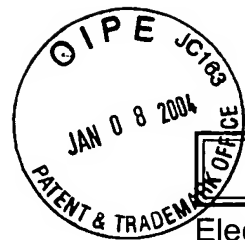


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	49	6384472	2002-05-07	HUANG
	50	6388336	2002-05-14	VENKATESHWARAN ET AL.

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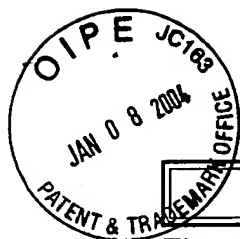
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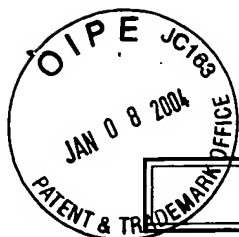


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<p>Application Number: 10/667759 </p> <p>Date: 2003-09-22</p> <p>First Named Applicant: Sean T. Crowley</p> <p>Confirmation Number: 1384</p> <p>Attorney Docket Number: AMKOR022CB</p>										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids3-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids3-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids3-usidst.xml									
	us-ids.dtd									
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Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

METHODS OF MAKING THIN INTEGRATED CIRCUIT
DEVICE PACKAGES WITH IMPROVED THERMAL
PERFORMANCE

Application Number: 10/667759
Confirmation Number: 1384
First Named Applicant: Sean Crowley
Attorney Docket Number: AMKOR022CB
Art Unit: 2811



Search string: (5640047 or 5641997 or 5643433 or 5644169
or 5646831 or 5650663 or 5661088 or 5665996
or 5673479 or 5683806 or 5689135 or 5696666
or 5701034 or 5703407 or 5710064 or 5723899
or 5724233 or 5736432 or 5745984 or 5753532
or 5753977 or 5766972 or 5770888 or 5776798
or 5783861 or 5801440 or 5814877 or 5814881
or 5814883 or 5814884 or 5817540 or 5818105
or 5821457 or 5821615 or 5834830 or 5835988
or 5844306 or 5856911 or 5859471 or 5866939
or 5871782 or 5874784 or 5877043 or 5886397
or 5886398 or 5894108 or 5897339 or 5900676
or 5903049 or 5903050).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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	50	5903050	1999-05-11	THURAIRAJARATNAM ET AL.

Signature

Examiner Name	Date